

Amendment to the Specification

Please replace Table 2 on page 22 with the following table.

REPLACEMENT SHEET

TABLE 2

Comparative Example											
	1	2	3	4	5	6	7	8	9	10	11
Phenol biphenylalkyl type epoxy resin	7.4	8.4		7.4	7.5	7.6	7.35	7.35	7.4	7.35	7.35
Biphenyl type epoxy resin											
Cresol novolac type epoxy resin			6.9								
Phenol biphenylalkyl resin	5.5			5.5	5.52	5.65	5.5	5.5	5.5	5.5	5.5
Phenolalkyl resin			6.0								
Phenol novolac resin		3.5									
Spherical fused silica	86.0	86.0	86.0	86.0	88.0	86.0	86.0	86.0	86.0	86.0	86.0
γ -glycidoxypolytrimethoxysilane	0.4	0.4	0.4		0.4		0.4	0.4	0.4	0.4	0.4
7-Me rcapto pro pyltrimethoxysilane				0.4							
Triphenylphosphine	0.2	0.15	0.15	0.2	0.06	0.2	0.2	0.2			
DBU									0.2		
Curing accelerator of formula C7)										0.25	
Curing accelerator of formula C8)											0.25
2,3-Dihydroxynaphthalene		0.05	0.05			0.05					
1,2-Dihydroxynaphthalene											
Catechol											
Pyrogallo l											
1,6-Dihydroxynaphthalene							0.05				
Resorcinol								0.05			
Carnauba wax	0.2	0.2	0.2	0.2	0.2	0.2	0.2	0.2	0.2	0.2	0.2
Carbon black	0.3	0.3	0.3	0.3	0.3	0.3	0.3	0.3	0.3	0.3	0.3
Spiral flow (cm)	80	76	71	62	114	76	78	81	68	89	77
Curing torque ratio (%)	65	67	70	62	7	66	65	64	57	85	88
Solder resistance-cracking	Chip delamination	4	2	chip	3		9	5	4	4	2
	Internal crack	0	10	exposure	0	Poor Releasing	0	0	0	0	0
Fire retardancy	V-0	V-1	HB	V-0		V-0	V-0	V-0	V-0	V-0	V-0